

SOT320-3

plastic quad flat package; 128 leads (lead length 1.95 mm);
body 28 x 28 x 3.4 mm; lead angle 60 deg

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QFP128
Package type industry code	QFP128
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-112
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	[tbd]	-	3.95	3.95	mm
A ₂	package height	3.15	-	3.4	3.7	mm
n ₂	actual quantity of termination	-	-	128	-	

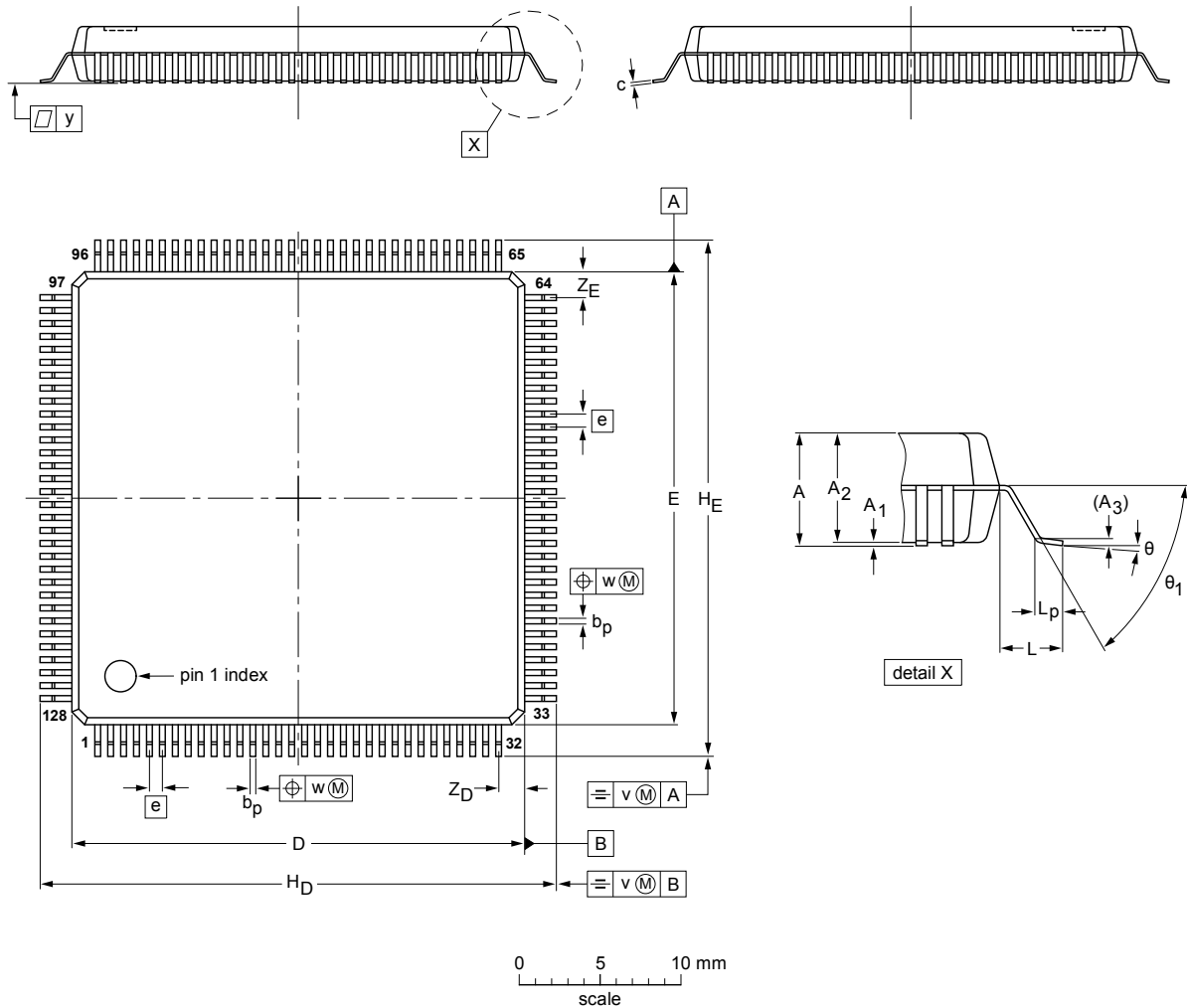


plastic quad flat package; 128 leads (lead length 1.95 mm); body 28 x 28 x 3.4 mm; lead angle 60 deg

2. Package outline

QFP128: plastic quad flat package;
128 leads (lead length 1.95 mm); body 28 x 28 x 3.4 mm; lead angle 60°

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ	θ ₁
mm	3.95	0.25 0.05	3.70 3.15	0.25	0.45 0.30	0.23 0.11	28.1 27.9	28.1 27.9	0.8	32.2 31.6	32.2 31.6	1.95	0.95 0.55	0.25	0.2	0.1	1.8 1.4	1.8 1.4	7° 0°	65° 55°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT320-3	---	MO-112				03-02-19

Fig. 1. Package outline QFP128 (SOT320-3)

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3. Soldering

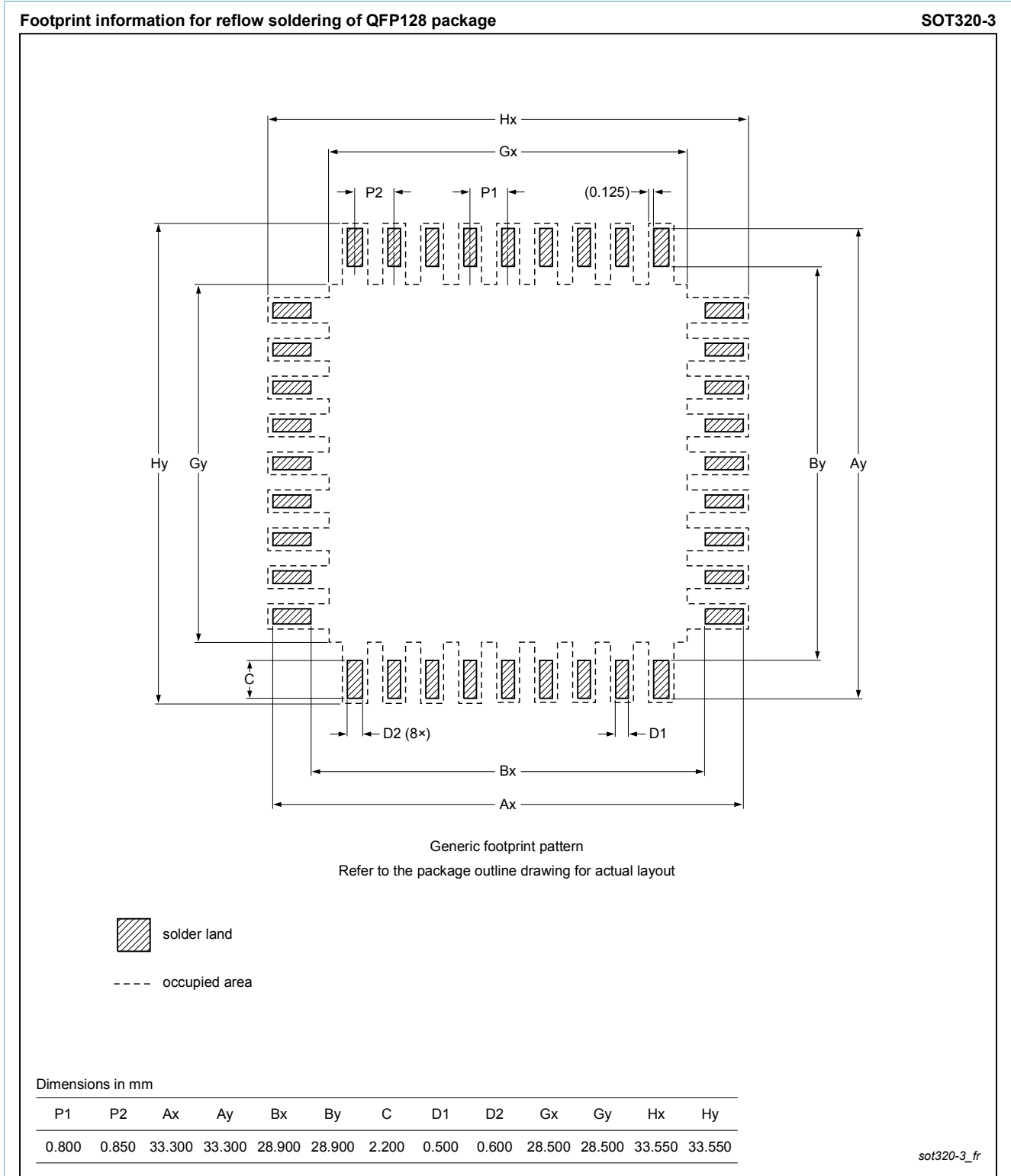


Fig. 2. Reflow soldering footprint for QFP128 (SOT320-3)

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deg

4. Legal information

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